

Amendments to the Claims:

This listing of claims replaces all prior versions and listings of claims in the application:

Listing of Claims:

1-5. (Cancelled)

6. (Currently amended) A recycling method for recycling waste particles comprising:
machining a crystal ingot into a wafer or machining a semiconductor wafer;
solidifying into a cake, particles generated by machining the crystal ingot or the
semiconductor wafer;
transporting the cake in a container such that where dryness is prevented; and
melting the cake.
7. (Currently amended) A recycling method for recycling waste particles comprising:
machining a crystal ingot into a wafer or machining a semiconductor wafer;
solidifying into a cake, particles generated by machining the crystal ingot or the
semiconductor wafer;
transporting the cake in a container such that where dryness is prevented; and
recycling said cake as an ingot.
8. (Currently amended) A recycling method for recycling waste particles comprising:
machining a crystal ingot into a wafer or machining a semiconductor wafer;
solidifying into a cake at a predetermined water content, particles generated by
machining the crystal ingot or the semiconductor wafer;
transporting the cake in a container such that where dryness is prevented; and
melting said cake to recycle said cake as an ingot.

9. (Currently amended) A method for fabricating a semiconductor ingot comprising: machining a crystal ingot into a wafer or machining a semiconductor wafer; solidifying into a cake at a predetermined water content and without any chemical reactions, particles generated by machining the crystal ingot or the semiconductor wafer; transporting the cake in a container such that where dryness is prevented; and melting said cake.

10. (Previously presented) A recycling method according to one of claims 6 to 8, wherein machining comprises abrading, grinding or polishing, dicing, back grinding or wafer polishing.

11. (Previously presented) A method according to claim 9, wherein machining comprises abrading, grinding or polishing, dicing, back grinding or wafer polishing.

12- 18. (Cancelled)

19. (Currently amended) A method for processing particles comprising: solidifying into a cake, particles that are generated by machining a crystal ingot into a wafer or machining a semiconductor wafer; transporting the cake in a container such that where dryness is prevented; and melting the cake into an ingot.

20. (Previously presented) A method according to claim 19, further comprising: solidifying said particles at a predetermined water content, without any chemical reactions.

21. (Previously presented) A method according to claim 19, wherein machining comprises abrading, grinding or polishing.

22. (Previously presented) A method according to claim 19, wherein machining said semiconductor wafer comprises dicing, back grinding or wafer polishing.

23. (Previously presented) A method according to claim 19, wherein said particles comprises Si flakes.

24. (Currently amended) A recycling method for recycling waste particles, comprising: transporting a cake in a container such that where dryness is prevented; and melting the cake which is produced by solidifying particles generated by machining a crystal ingot into a wafer or machining a semiconductor wafer.

25. (Currently amended) A recycling method for recycling waste particles comprising: transporting a cake in a container such that where dryness is prevented; and melting the cake to recycle the cake as an ingot, said cake produced by solidifying particles generated by machining a crystal ingot or a semiconductor wafer at a predetermined water content.

26. (Currently amended) A method for fabricating a semiconductor ingot comprising: transporting a cake in a container such that where dryness is prevented; and melting the cake which is produced by solidifying particles generated by machining a crystal ingot or a semiconductor wafer at a predetermined water content and without any chemical reactions.

27. (Currently amended) A method for processing particles comprising: transporting a cake in a container such that where dryness is prevented; and melting the cake into an ingot, said cake produced by solidifying particles that are generated by machining a crystal ingot into a wafer or machining a semiconductor wafer.